



Silicon Crystal & Compound Semiconductor

➤ Gallium Phosphide (GaP) Substrate

Gallium Phosphide (GaP) Substrate is an orange-yellow semi-translucent material foamed by high purity of Gallium and Phosphorus, grown by Liquid Encapsulated Czochralski (LEC) method, which is a proven important semiconductor material and is widely used for LED industry.



No.	Items	Standard Specifications
1	Diameter mm	2" /50.8±0.5
2	Growth Method	LEC
3	Conductivity	P/N/Semi-insulating
4	Orientation	<100>, <111>
5	Thickness μm	(300-400)±20
6	Resistivity	0.003-0.3
7	OF/IF Flat mm	16±2/8±1, EJ or as per SEMI
8	Hall Mobility cm ² /v.s	≥100
9	Carrier Concentration atoms/cm ³	(2-20)E17
10	TTV μm max	10
11	Bow μm max	30
12	Warp μm max	30
13	EPD cm ⁻²	≤2E5
14	Surface Finish	P/E, P/P, E/E
15	Packing	Single wafer container inside, carton box outside.

➤ Gallium Antimonide (GaSb) Substrate

Gallium Antimonide (GaSb) Substrate is a compound material foamed by high purity Gallium and Antimony elements, grown by Liquid Encapsulated Czochralski (LEC) method, which is widely applied for optoelectronics industry. 2" 3" and 4" is available.



No.	Items	Standard Specifications		
1	Size	2"	3"	4"
2	Diameter mm	50.8±0.5	76.2±0.5	100±0.5
3	Growth Method	LEC	LEC	LEC
4	Conductivity	P/N	P/N	P/N
5	Orientation	<100>, <111>		
6	Thickness μm	500±25	600±25	800±25
7	Flats Option	EJ or as per SEMI		
8	Orientation Flat mm	16±2	22±2	32±2
9	Identification Flat mm	8±1	11±1	18±1
10	Hall Mobility cm ² /v.s	600-3500 or as required		
11	Carrier Concentration atoms/cm ³	(1-100)E17 or as required		
12	TTV μm max	15	15	15
13	Bow μm max	15	15	15
14	Warp μm max	20	20	20
15	EPD cm ⁻² max	3000	3000	3000
16	Surface Finish	P/E, P/P, E/E	P/E, P/P, E/E	P/E, P/P, E/E
17	Packing	Single wafer container inside, carton box outside.		

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